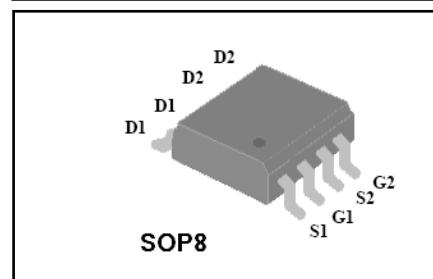
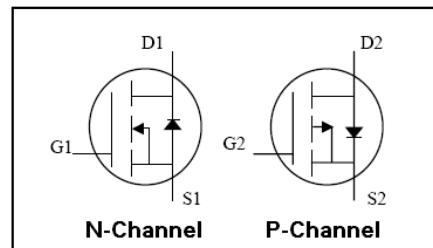


Features

- ◆ N-CH: 30V/6A, $R_{DS(ON)}=30m\Omega$ (Typ)@ $V_{GS}=4.5V$
- ◆ P-CH: -30V/-5.2A, $R_{DS(ON)}=45m\Omega$ (Typ)@ $V_{GS}=-4.5V$
- ◆ Low On-Resistance
- ◆ Low V_{th} Application
- ◆ Fast Switching
- ◆ 150°C Operating Temperature
- ◆ Lead-Free, Green Product

Pin Description



Description

VS4606AS designed by the trench processing techniques to achieve extremely low on-resistance. And fast switching speed and improved transfer effective . These features combine to make this design an extremely efficient and reliable device for variety of DC-DC applications.

Absolute Maximum Ratings

Symbol	Parameter	Rating		Unit	
		NMOS	PMOS		
Common Ratings ($T_c=25^\circ C$ Unless Otherwise Noted)					
V_{GS}	Gate-Source Voltage	± 30	± 30	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	30	-30	V	
T_J	Maximum Junction Temperature	175		°C	
T_{STG}	Storage Temperature Range	-50 to 150		°C	
I_s	Diode Continuous Forward Current ^①	$T_c=25^\circ C$	6	-5.2	A

Mounted on Large Heat Sink

I_{DM}	Pulse Drain Current Tested ^②	$T_c=25^\circ C$	20	18	A
I_D	Continuous Drain Current($V_{GS}=-10V$)	$T_c=25^\circ C$	6.0	-5.2	A
		$T_c=100^\circ C$	3.6	-3.5	
P_D	Maximum Power Dissipation	$T_c=25^\circ C$	2		W
$R_{\theta JA}$		62.5		°C/W	

N-Channel

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ $I_D=250\mu\text{A}$	30	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current ($T_c=25^\circ\text{C}$)	$V_{\text{DS}}=30\text{V}$, $V_{\text{GS}}=0\text{V}$	--	--	1	μA
	Zero Gate Voltage Drain Current ($T_c=125^\circ\text{C}$)	$V_{\text{DS}}=30\text{V}$, $V_{\text{GS}}=0\text{V}$	--	--	100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 16\text{V}$, $V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=250\mu\text{A}$	0.6	0.9	1.2	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=4.5\text{V}$, $I_D=4\text{A}$	--	30	40	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=3.3\text{V}$, $I_D=2\text{A}$	--	32	60	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	--	420	--	pF
C_{oss}	Output Capacitance		--	60	--	pF
C_{rss}	Reverse Transfer Capacitance		--	35	--	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=15\text{V}$, $I_D=1\text{A}$, $V_{\text{GS}}=4.5\text{V}$	--	11	--	nC
Q_{gs}	GateSource Charge		--	3.0	--	nC
Q_{gd}	GateDrain Charge		--	4.0	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turnon Delay Time	$V_{\text{DD}}=15\text{V}$, $I_D=1\text{A}$, $R_G=3.3\Omega$, $V_{\text{GS}}=4.5\text{V}$	--	14	--	nS
t_r	Turnon Rise Time		--	16	--	nS
$t_{\text{d(off)}}$	TurnOff Delay Time		-	28	--	nS
t_f	TurnOff Fall Time		--	11	--	nS
Source Drain Diode Characteristics						
I_{SD}	Sourcedrain current(Body Diode) ^①	$T_c=25^\circ\text{C}$	8	--	--	A
V_{SD}	Forward on voltage	$T_j=25^\circ\text{C}$, $I_{\text{SD}}=3\text{A}$, $V_{\text{GS}}=0\text{V}$	--	0.7	1.3	V

Notes:

① Pulse test ; Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

② Pulse width limited by maximum allowable junction temperature

P-Channel

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ $I_D=-250\mu\text{A}$	-30	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current ($T_c=25^\circ\text{C}$)	$V_{\text{DS}}=-30\text{V}$, $V_{\text{GS}}=0\text{V}$	--	--	1	μA
	Zero Gate Voltage Drain Current ($T_c=125^\circ\text{C}$)	$V_{\text{DS}}=-30\text{V}$, $V_{\text{GS}}=0\text{V}$	--	--	100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 12\text{V}$, $V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=-250\mu\text{A}$	-0.6	-0.9	-1.2	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=-4.5\text{V}$, $I_D=-3\text{A}$	--	45	65	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=-3.3\text{V}$, $I_D=-2\text{A}$	--	55	75	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	--	500	--	pF
C_{oss}	Output Capacitance		--	80	--	pF
C_{rss}	Reverse Transfer Capacitance		--	65	--	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=-15\text{V}$, $I_D=-1\text{A}$, $V_{\text{GS}}=-4.5\text{V}$	--	12	--	nC
Q_{gs}	Gate-Source Charge		--	4	--	nC
Q_{gd}	Gate-Drain Charge		--	6	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=-15\text{V}$, $I_D=-1\text{A}$, $R_G=3.3\Omega$, $V_{\text{GS}}=-4.5\text{V}$	--	8.2	--	nS
t_r	Turn-on Rise Time		--	7.3	--	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	33	--	nS
t_f	Turn-Off Fall Time		--	28	--	nS
Source- Drain Diode Characteristics						
I_{SD}	Source-drain current(Body Diode)	$T_c=25^\circ\text{C}$	-5.8 ^①	--		A
V_{SD}	Forward on voltage	$T_j=25^\circ\text{C}$, $I_{\text{SD}}=-3\text{A}$ $V_{\text{GS}}=0\text{V}$	--	-0.75	-1.3	V

Notes:

① Pulse test ; Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

② Pulse width limited by maximum allowable junction temperature.

N-Channel Typical Characteristics

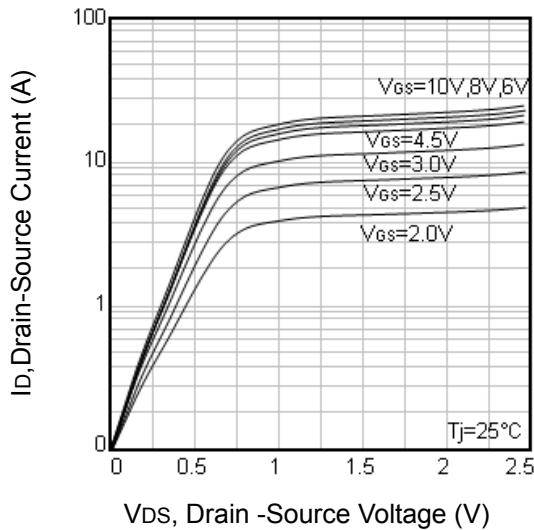


Fig1. Typical Output Characteristics

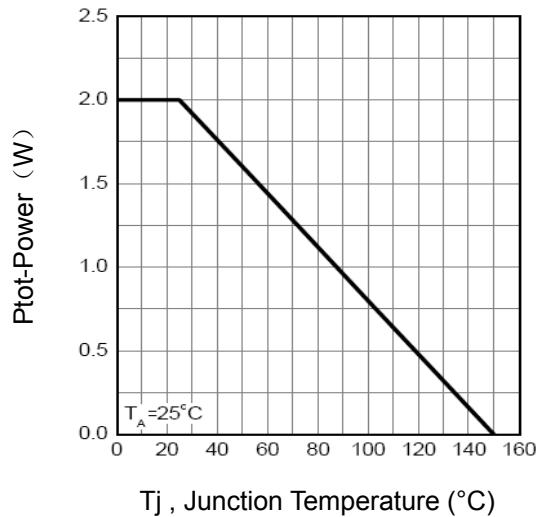


Fig2. Power Dissipation

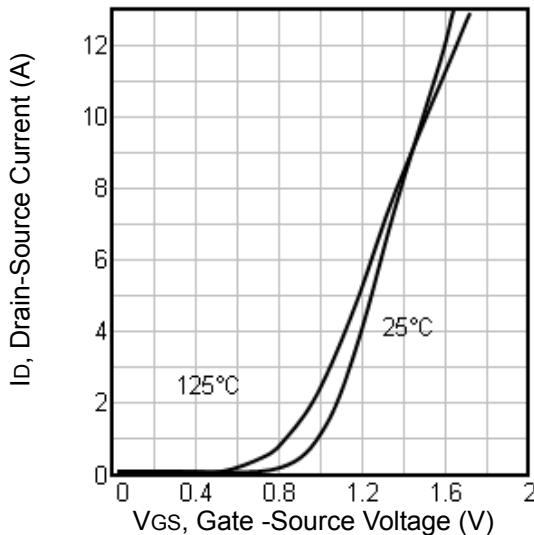


Fig3. Typical Transfer Characteristics

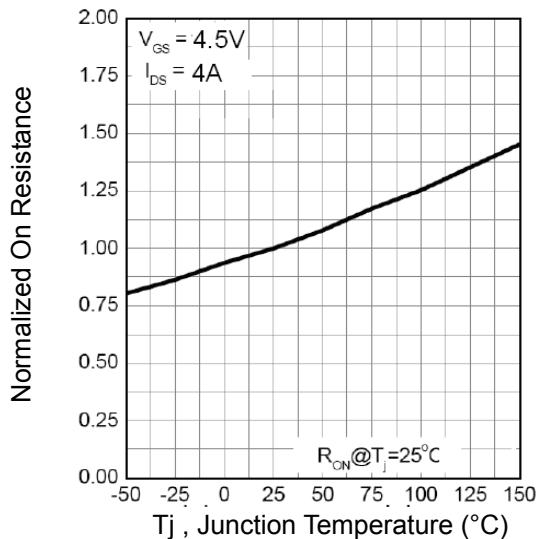


Fig4. Normalized On-Resistance Vs. Temperature

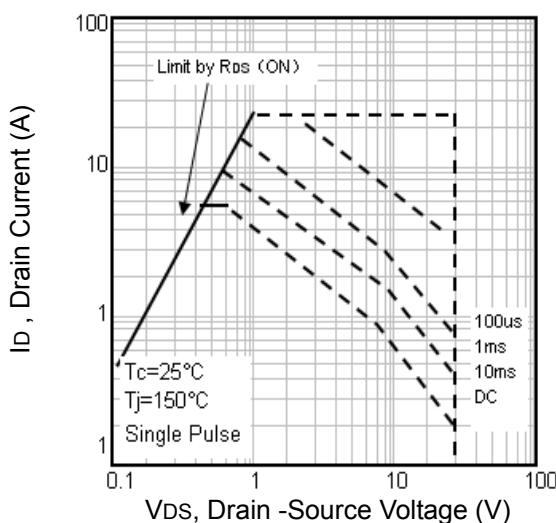


Fig5. Maximum Safe Operating Area

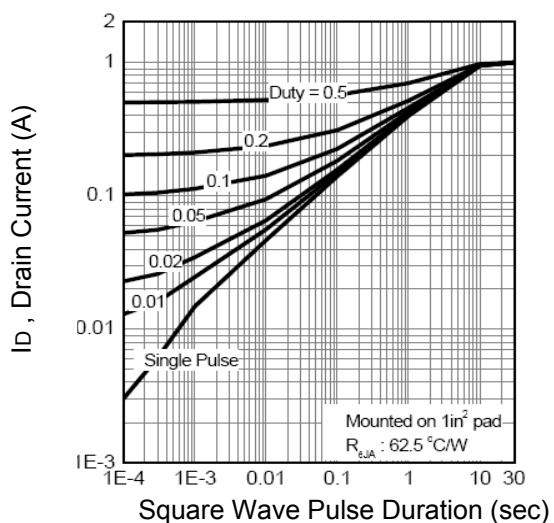


Fig6. Thermal Transient Impedance

N-Channel Typical Characteristics

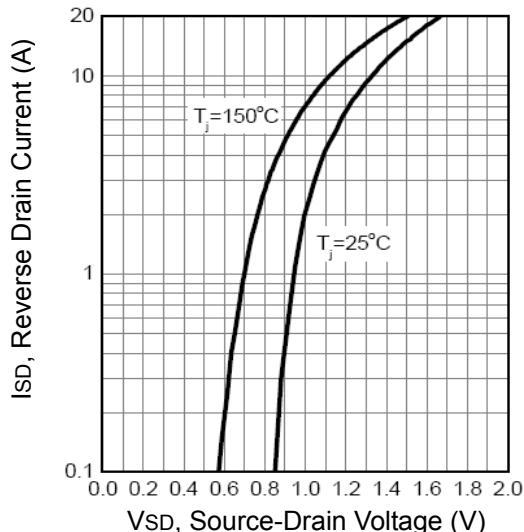


Fig7. Typical Source-Drain Diode Forward Voltage

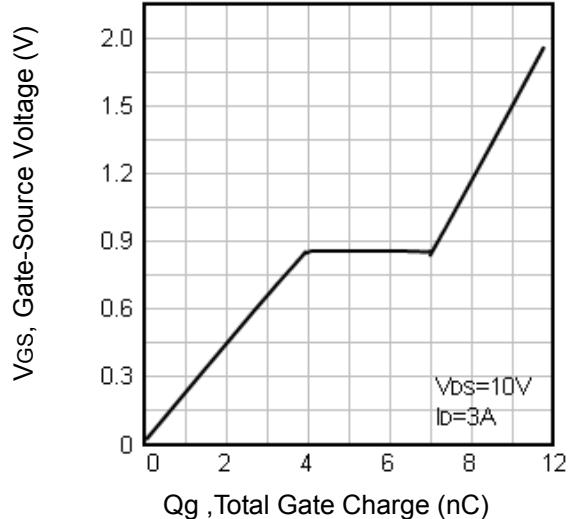


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

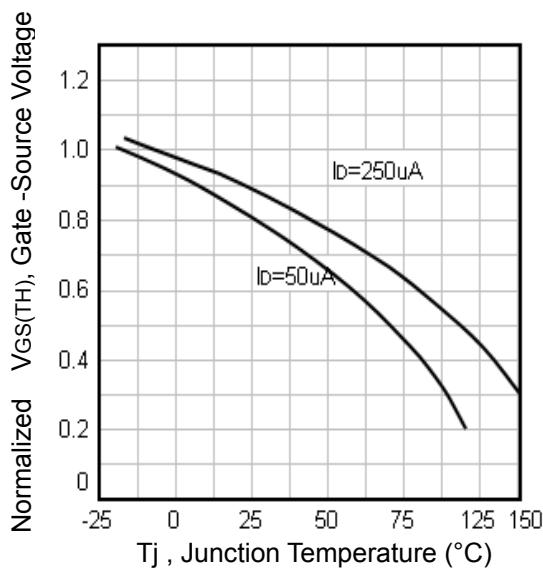


Fig9. Threshold Voltage Vs. Temperature

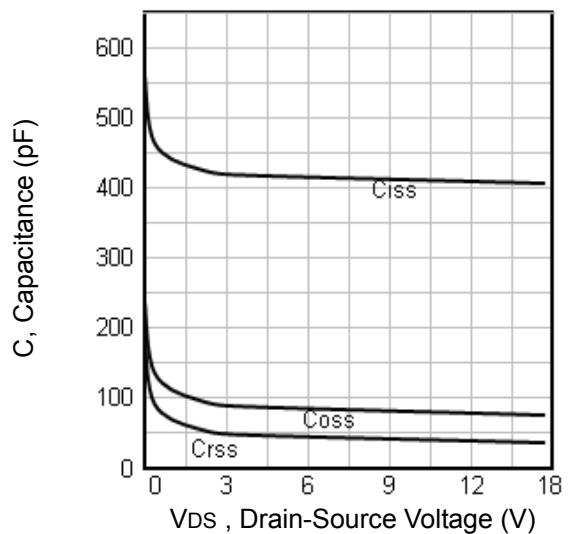


Fig10. Typical Capacitance Vs.Drain-Source Voltage

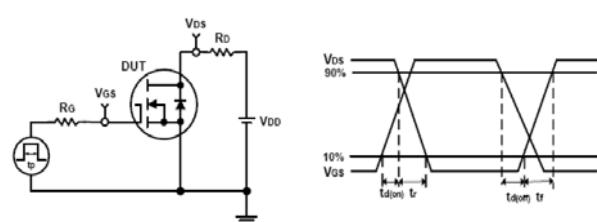


Fig11. Switching Time Test Circuit and waveforms

P-Channel Typical Characteristics

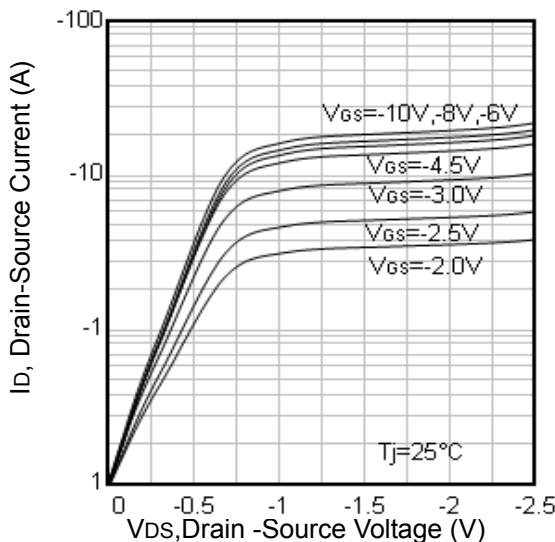


Fig1. Typical Output Characteristics

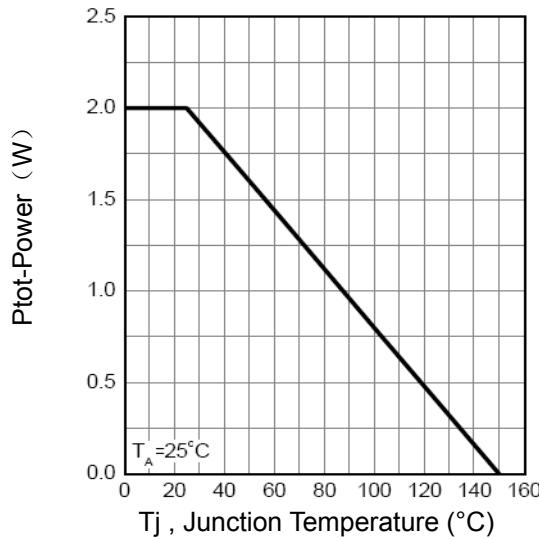


Fig2. Power Dissipation

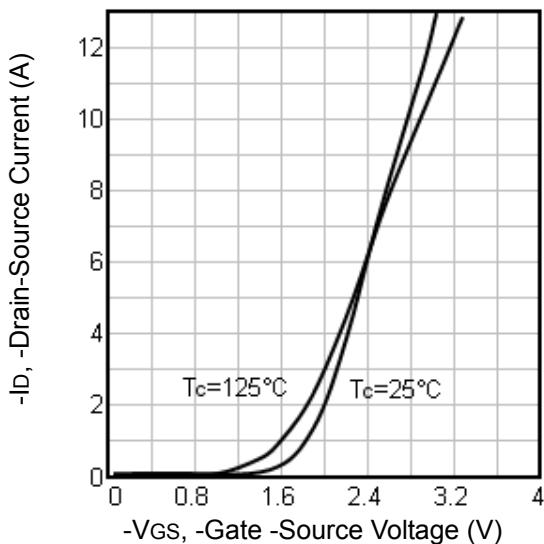


Fig3. Typical Transfer Characteristics

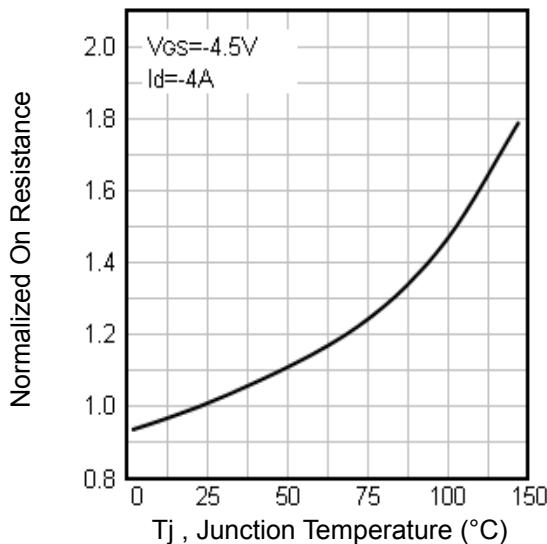


Fig4. Normalized On-Resistance Vs. Temperature

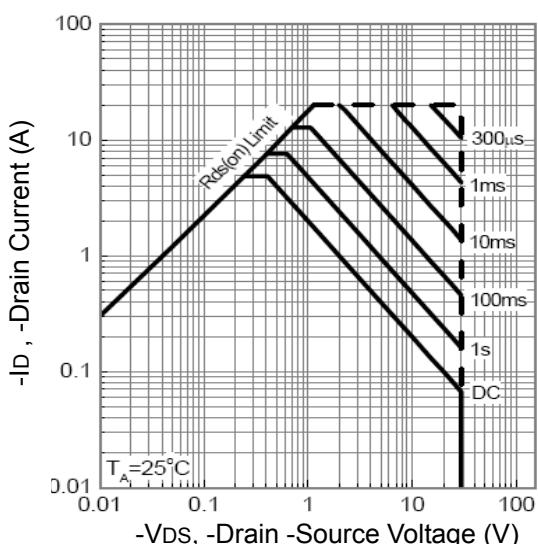


Fig5. Maximum Safe Operating Area

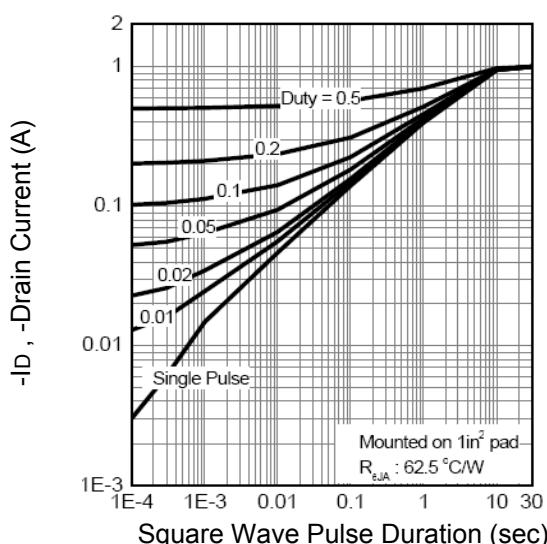


Fig6. Thermal Transient Impedance

P-Channel Typical Characteristics

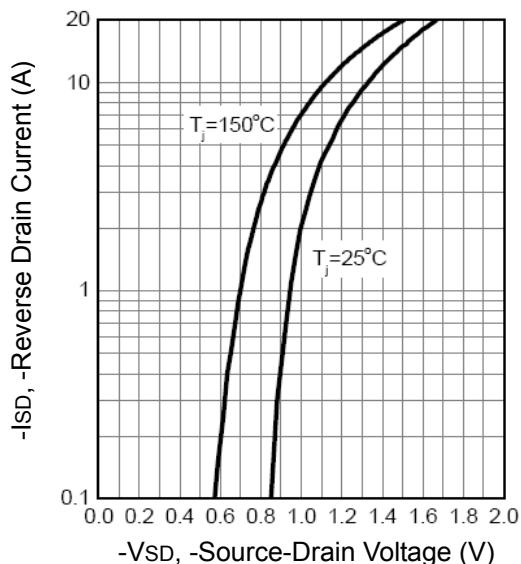


Fig7. Typical Source-Drain Diode Forward Voltage

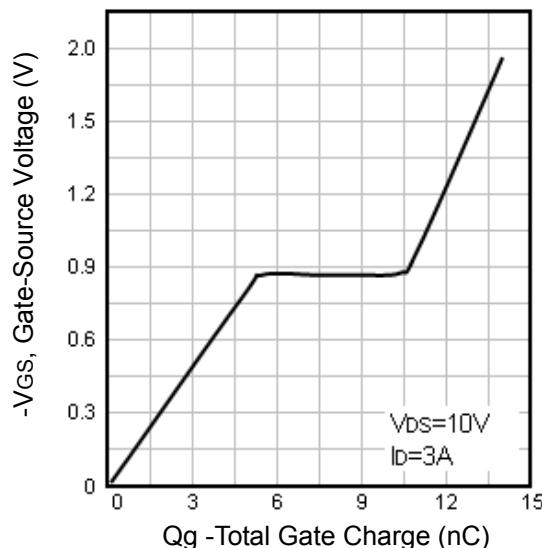


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

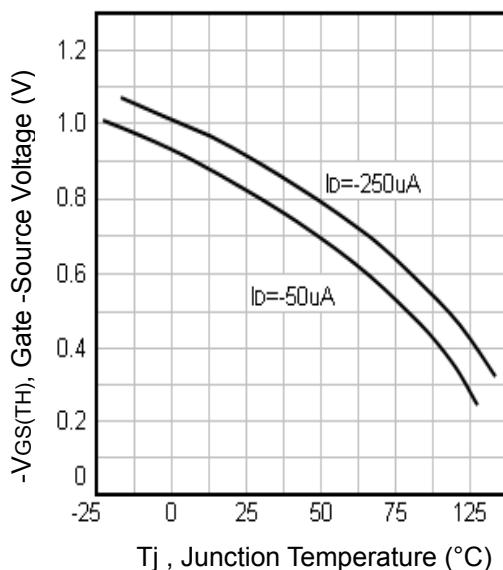


Fig9. Threshold Voltage Vs. Temperature

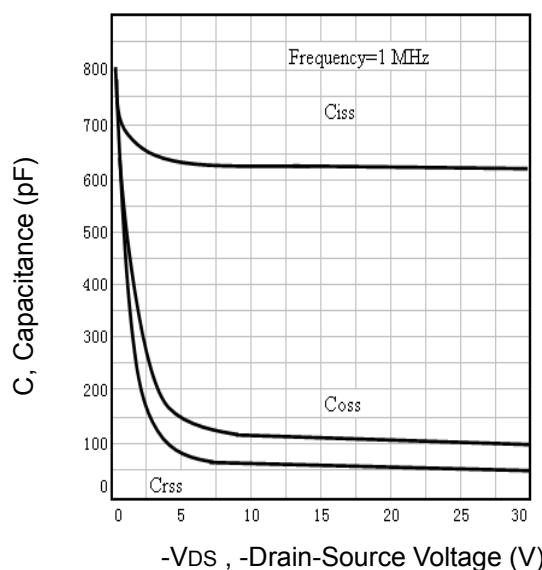


Fig10. Typical Capacitance Vs.Drain-Source Voltage

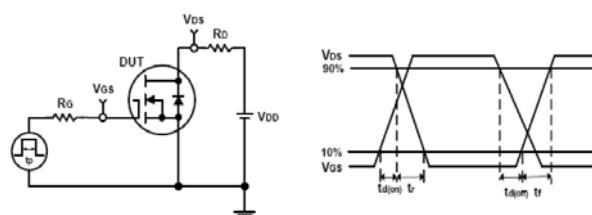
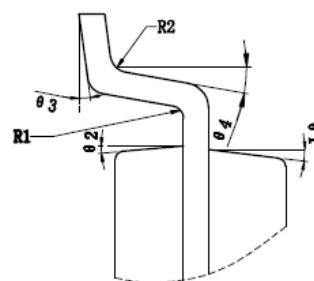
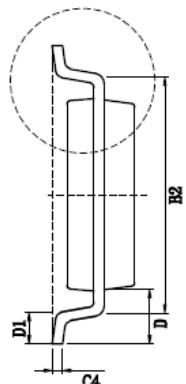
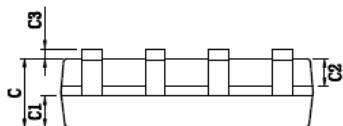
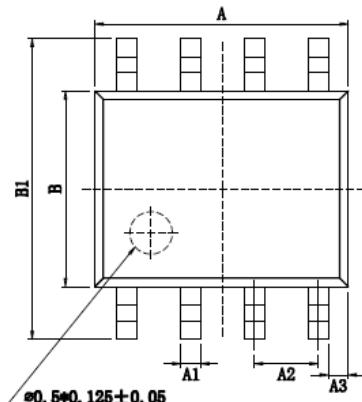


Fig11. Switching Time Test Circuit and waveforms

SOP8 Mechanical Data



Symbol	Dimensions In Millimeters		
	Min	Nom	Max
A	4.800	4.900	5.000
A1	0.356	0.406	0.456
A2			1.270Typ.
A3			0.345Typ.
B	3.800	3.900	4.000
B1	5.800	6.000	6.200
B2			5.00Typ.
C	1.300	1.400	1.500
C1	0.550	0.600	0.650
C2	0.550	0.600	0.650
C3	0.050	--	0.200
C4			0.203Typ.
D			1.050Typ.
D1	0.400	0.500	0.600
R1	0.200Typ.		
R2	0.200Typ.		
Θ_1	17°Typ.		
Θ_2	13°Typ.		
Θ_3	0°~ 8°Typ.		
Θ_4	4°~ 12°Typ.		

Order Information

Product	Marking	Package	Packaging	Min Unit Quantity
VS4606AS	VS4606AS	SOP8	3000/Reel	6000

Customer Service

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